

Bill of Materials

TI DESIGNS
Part #
Literature #

DESIGNATOR	QUANTITY	DESCRIPTION	ITEM/PART NUMBER	FOOTPRINT
C1, C2	2	Passive CAP	2.2uF	1206 (Pol)
C3, C4, C5, C6, C7, C8, C9, C10, C11, C12, C13	11	Passive CAP	0.1uF	0603
J1	1	SMA Connector	IN A	SMA - Surface mount
J2	1	SMA Connector	OUT A	SMA - Surface mount
J3	1	SMA Connector	IN B	SMA - Surface mount
J4	1	SMA Connector	OUT B	SMA - Surface mount
JP1, JP2, JP3, JP4	4	Jumpers	3 Pin Jumper	3POS_JUMP -Small
L1, L2	2	Inductor	LI1206B900R	1206 -S
P1	1	3 CONTACT TERMINAL BLOCK		Term Block 3 pins 3.5mm
R1, R16	2	Passive Resistor	49.9Ohms	0603
R2, R17	2	Passive Resistor	24.9Ohms	0603
R3, R7, R8, R14, R15, R18	6	Passive Resistor	9530hms	0603
R4, R11	2	Passive Resistor	1KOhms	0603
R5, R13	2	Passive Resistor	50.1Ohms	0603
R6, R12	2	Passive Resistor	19.45Ohms	0603
R9, R10	2	Passive Resistor	NC	0603
U1	1	Dual Port Differential VDSL2 Line Driver Amplifiers	OPA2683IDGST	MSOP-10(DGS)
U2	1	Dual SPST Analog Switch	TS5A23166	SO-8

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